

ABSTRACT OF THE DISCLOSURE

In one embodiment, an interconnect line on one level of an integrated circuit is electrically coupled to another interconnect line on another level. The two layers of interconnects may be coupled together using a via. To reduce capacitance between the interconnect lines, an air core is formed between them. The air core may be formed by using a chemistry that includes a noble gas fluoride to etch a sacrificial layer between the interconnect layers.

5

1002.000400